



## Material Content Data Sheet



<b>Sales Product Name</b>		TLE5206-2S		<b>Issued</b>		27. September 2017		
<b>MA#</b>		MA001209624						
<b>Package</b>		PG-TO220-7-12		<b>Weight*</b>		2124.31 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	11.039	0.52	0.52	5197	5197
leadframe	non noble metal	iron	7439-89-6	0.908	0.04		427	
	inorganic material	phosphorus	7723-14-0	0.272	0.01		128	
	non noble metal	copper	7440-50-8	906.793	42.69	42.74	426865	427420
wire	non noble metal	aluminium	7429-90-5	2.781	0.13	0.13	1309	1309
encapsulation	organic material	carbon black	1333-86-4	8.796	0.41		4141	
	plastics	epoxy resin	-	96.759	4.55		45548	
	inorganic material	silicondioxide	60676-86-0	480.862	22.64	27.60	226361	276050
leadfinish	non noble metal	tin	7440-31-5	23.005	1.08	1.08	10830	10830
plating	non noble metal	nickel	7440-02-0	0.216	0.01		102	
	inorganic material	phosphorus	7723-14-0	0.001	0.00	0.01	426864	102
solder	noble metal	silver	7440-22-4	0.232	0.01		109	
	non noble metal	tin	7440-31-5	0.186	0.01		88	
	non noble metal	lead	7439-92-1	8.877	0.42	0.44	4179	4376
heatspreader	non noble metal	iron	7439-89-6	0.584	0.03		275	
	inorganic material	phosphorus	7723-14-0	0.175	0.01		82	
	non noble metal	copper	7440-50-8	582.824	27.44	27.48	274359	274716
*deviation	< 10%				Sum in total:	100.00		1000000

### Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com